EPOXY TECHNOLOGY

Product Information Sheet

EPO-TEK® EJ2108

Date:	October 2019	
Rev:	XI	
No. of Components:	Two	
Mix Ratio by Weight:	2 : 1	
Specific Gravity:	Part A: 3.35	Part B: 3.76
Pot Life:	1 Hour	
Shelf Life- Bulk:	Six months at room temperature	

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
80°C / 2 Hours
23°C / 3 Days

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: Two component flexible, silver-filled, electrically and thermally conductive low temperature curing adhesive.

Typical Properties: Cure condition: varies as required Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Silver	Part B: Silver	
* Consistency:	Smooth highly thixotropic paste		
* Viscosity (23°C) @ 10 rpm:	8,000-20,000	cPs	
Thixotropic Index:	3.0		
* Glass Transition Temp:	≥ 30	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	56	x 10^{-6} in/in°C	
Above Tg:	223	x 10^{-6} in/in°C	
Shore D Hardness:	55		
Shore A Hardness:	93		
Lap Shear @ 23°C:	796	psi	
Die Shear @ 23°C:	≥ 5	Kg	1,778 psi
Degradation Temp:	276	°C	
Weight Loss:			
@ 200°C:	0.26	%	
@ 250°C:	0.62	%	
Suggested Operating Temperature:	< 175	°C (Intermittent)	
Storage Modulus:	2,553	psi	
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	4.0	W/mK
*Volume Resistivity @ 23°C (150°C/1 Hour):	≤ 0.0001	Ohm-cm
Volume Resistivity @ 23°C (80°C/2 Hours):	≤ 0.0002	Ohm-cm
Volume Resistivity @ 23°C (25°C/60%RH/3 Days) :	≤ 0.009	Ohm-cm

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